

Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		
Working Peak Reverse Voltage	V_{RWM}	40	V
DC Blocking Voltage	V_{RM}		
Maximum Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/µs
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Rectified Output Current	lo	3	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	45	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 7) Thermal Resistance Junction to Ambient (Note 8) Thermal Resistance Junction to Case (Note 8)	$egin{array}{l} R_{ heta JS} \ R_{ heta JA} \ R_{ heta JC} \end{array}$	5 124 14.3	°C/W
Power Dissipation (Note 8) $@T_A = +25^{\circ}C$	P _D	1.2	W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

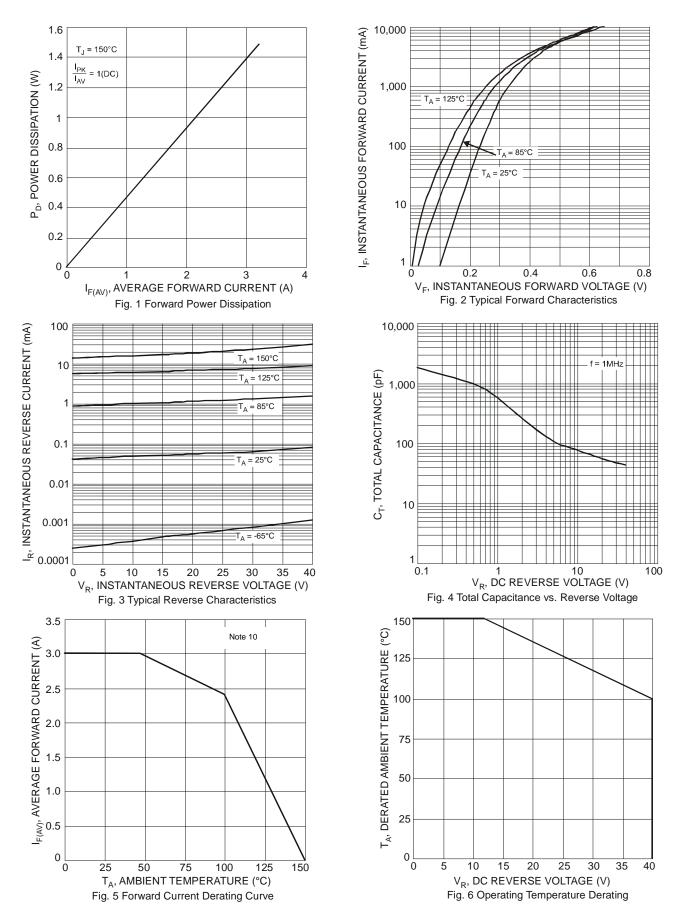
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 9)	V _{(BR)R}	40	_	1	V	$I_R = 0.4 \text{mA}$
Forward Voltage Drop	V _F	- - -	0.30 0.33 0.43 -	0.35 0.38 0.50 0.48	V	I _F = 0.5A, T _J = +25°C I _F = 1.0A, T _J = +25°C I _F = 3.0A, T _J = +25°C I _F = 3.0A, T _J = +125°C
Leakage Current (Note 9)	I _R	_	45 80 9	250 400 40	μΑ μΑ mA	$V_R = 5V$, $T_J = +25$ °C $V_R = 40V$, $T_J = +25$ °C $V_R = 40V$, $T_J = +125$ °C

Notes:

- 7. Theoretical $R_{\theta,JS}$ calculated from the top center of the die straight down to the PCB cathode tab solder junction.
- 8. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. FR-4 PCB, 2 oz. Copper, single side 16 x MRP, 1" x 1" PC Board.

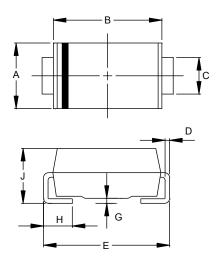






Package Outline Dimensions

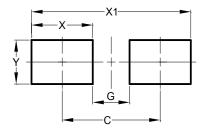
Please see http://www.diodes.com/package-outlines.html for the latest version.



SMA				
Dim	Min	Max		
Α	2.29	2.92		
В	4.00	4.60		
C	1.27	1.63		
D	0.15	0.31		
Е	4.80	5.59		
G	0.05	0.20		
Н	0.76	1.52		
J	1.96	2.40		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Υ	1.70



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